# Product Change Notification (PCN)

**Date:** July 31st, 2015          PCN TRACKING NO: PCN---------31072015

**Subject:** Product Change Notification (PCN) for Alliance SDRAM's (x32)

| Description of Change: | Product will only be offered in a new Die Revision |
|---|---|
| Reason for Change | Part # change to new process technology to 63nm |
| Traceability, Guidelines (lot, date code, markings, shipment date) | Traceable through marketing part # |
| Updated Datasheet | Part # has been changed and updated datasheets are posted on our website http://www.alliancememory.com/products/s_dram.as |
| Summary of Changes between New and Old part numbers | See table 1 Below |

## Table 1

| Density | Organization | Alliance Part Number | Alliance New Part |
|---|---|---|---|
| 64M | 2M x 32 | AS4C2M32S-7TCN | AS4C2M32SA-7TCN |
| 64M | 2M x 32 | AS4C2M32S-6TCN | AS4C2M32SA-6TCN |
| 64M | 2M x 32 | AS4C2M32S-6TIN | AS4C2M32SA-6TIN |
| 64M | 2M x 32 | AS4C2M32S-5TCN | AS4C2M32SA-5TCN |
| 128M | 4M x 32 | AS4C4M32S-7TCN | AS4C4M32SA-7TCN |
| 128M | 4M x 32 | AS4C4M32S-6TCN | AS4C4M32SA-6TCN |
| 128M | 4M x 32 | AS4C4M32S-6TIN | AS4C4M32SA-6TIN |
| **New offering** | | | |
| 256M | 8M x 32 | | AS4C8M32SA-7TCN |
| 256M | 8M x 32 | | AS4C8M32SA-6TIN |

| Last Time Buy Date: | October 1st, 2015 |
|---|---|
| Last Time Ship Date: | March 1st, 2016 |
| Sample Availability   Date (2M x 32-64M) | July 31st, 2015 |
| Sample Availability   Date (4M x 32-128M) | August 31st, 2015 |
| Sample Availability   Date (8M x 32-256M) New Part | October 31st, 2015 |
| PCN Effective   Date | July 31st, 2015 |

**\* Any orders after October 1st, 2015 are Non-Cancelable/Non– Returnable and cannot be changed**

Dear Valued Customer:

This letter provides End–of–Life (EOL) notice of SDRAM products with an x 32 organization. These products will move to new 'A' die revision in Q1-2016.

The delivery deadline is March 1$^{st}$, 2016 with last time buy (LTB) deadline on October 1st, 2015. Please note that the standard shipment dates will apply in general and extended delivery dates must be pre-arranged and accepted in writing by Alliance Memory Management.

Regarding the replacement, Alliance Memory has provided the new 63nm technology product line-up (refer to Table 1 above). The 'A' die products will provide better cost and performance. Samples will be available soon for customers to start verification procedures.

We are excited to offer our new 8M x 32 TSOP product that will add to our already existing leadership position in the SDRAM market.

Please contact your local Alliance Memory representative if you have any questions regarding this information

Yours sincerely

David Bagby
President
**Alliance Memory Inc.**